| ASSOCIATION CONN ELECTRONICS IND | Material Composi © Copyright 2005. IPC, international and Pan-Ar | tion Dec Bannockb merican co | laration urn, Illinois. A pyright conver | ll rights reserved u ntions. | under both | This docume level parts, t | ent is a declara he declaration | ation c i encoi | of the substances mpasses all lowe | within th r level ma | e manufactur aterials for wi | er listed in hich the m | tem. Note: if nanufacturer h | the item is an as as engineering | sembly with lowe responsibility. |
|-------------------------------------|--|------------------------------------|---|------------------------------|-------------------------|--|--|--------------------|---------------------------------------|---------------------------------|---------------------------------|----------------------------|---------------------------------|-------------------------------------|----------------------------------|
| 1752-21.1 | | | | | Form Type Distribute | * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi | | | | | als and Mfg Information | | | | |
| Supplier Inf | formation | | | | | | | | | | | | | | |
| Company name | e* | Company unique ID | | | | Unique ID Authority | | | | | Response Date* | | | | |
| onsemi | | | | | | | | | | | 2024-04-30 | | | | |
| Contact Name | | Title - Contact | | | | Phone - Contact* | | | | | Email - Contact* | | | | |
| Product-Env-S | Stewards | | Product Enviro Compliance | | | | NA | | | | Product-Env-Stewards@onsemi.com | | | | |
| Authorized Rej | presentative* | | Title - Representative | | | | Phone - Representative* | | | | Email - Representative* | | | | |
| Product-Env-S | Stewards | Product Enviro Compliance | | | | NA | | | | Product-Env-Stewards@onsemi.com | | | | | |
| Req | Requester Item Number Mfr Item | | Number Mfr Item Name | | | | Effective Date Version Manufacturing S | | uring Site | Weight* | | UOM | Unit Type | | |
| | BAY73 | | | 125V GP DIODE DO-35 | | | 2024-04-30 | | | CN2 | | | 109.66989 | mg | Each |
| /Ianufactur | ring Proccess Information | n | | | | | | | | | | ł | | | |
| Tern | Terminal Plating / Grid Array Material | | Terminal Base Alloy J-STD-02 | | J-STD-020 MSI | L Rating | Peak Process | | s Body Temperature Max Time | | Гіте at Peak | Temperat | ure Numbe | r of Reflow Cyc | eles |
| Matte Tin (Sn) - annealed | | С | CU Alloy NA | | | 0 C | | 30 seco | | secon | ds 3 | | | | |
| omments | | | | | | | | | | | | | | | |
| | | | | | | | | | | | | | | | |
| or more infor | mation regarding material con | nposition j | please refer to | page 3 | | | | | | | | | | | |

| RoHS Material Composition Declaration | | | | Declaration Type * | Detailed | | | | | |
|---|--|--|--|---|---|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS Directive 2011/65/EU | | mium (Cr6+), Polybrominated Biphenyls (| | dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-ethers) | | | | | | |
| cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexcess encompass all such components.Supplier cert as of the date that Supplier completes this for Company acknowledges that Supplier may ha independently verified information provided certification in this paragraph.If the Company | ted biphenyls and/or polybrominated dip of an applicable quantity limit, please in ifies that it gathered the information it pr m.Supplier acknowledges that Company ve relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr source of the Supplier's liability and the | henyl ethers (each a "RoHS restricted subs ndicate below which, if any, RoHS exempt ovides in this form using appropriate meth will rely on this certification in determinin ers in completing this form, and that Suppl num, itssuppliers have provided certificatio eement with respect to the identified part,t Company's remedies for issues that arise r | stance") in exce ion you believe ods to ensure i g the compliar ier may not ha ons regarding t he terms and co | ropean Union member states) of the part identifiess of the applicable quantity limit identified able may apply. If the part is an assembly with low is accuracy and that such information is true and ce of its products with European Union member independently verified such information. How heir contributions to the part, and those certifica onditions of that agreement, including any warra nation the Supplier provides in this form. In the | ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the inty rights and/or remedies provided as part of | | | | | |
| RoHS Declaration * 4 - Item(s |) does not contain RoHS restricted subst | ances per the definition above except for se | elected exempt | ions Supplier Acceptance | * Accepted | | | | | |
| Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound. | | | | | | | | | | |
| Exemption List Version | EL-2011/534/EU | | | | | | | | | |
| Declaration Signature | | | | | | | | | | |
| Instructions: Complete all of the required Requester) and click on Submit Form to ha | | | ice drop-dowi | n. This will display the signature area. Digital | ly sign the declaration (if required by the | | | | | |
| Supplier Digital Signature R | astislav Drska | Le | | | | | | | | |

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level | Substance | CAS | Exempt | Weight | Unit of Measure |
|----------------------|----------|-----------------|----------|--|------------------|--------|--------|-----------------|
| CSS Wire | 75.0 | mg | Supplier | Iron (Fe) | 7439-89-6 | | 63.75 | mg |
| | | | Supplier | Copper (Cu) | 7440-50-8 | | 11.25 | mg |
| Die | 0.024358 | mg | Supplier | Titanium (Ti) | 7440-32-6 | | 0 | mg |
| | | | Supplier | Silver (Ag) | 7440-22-4 | | 0.0115 | mg |
| | | | Supplier | Silicon (Si) | 7440-21-3 | | 0.0127 | mg |
| | | | В | Nickel (Ni) | 7440-02-0 | | 0.0001 | mg |
| Dumet Wire | 8.5 | mg | Supplier | Manganese (Mn) | 7439-96-5 | | 0.085 | mg |
| | | | Supplier | Silicon (Si) | 7440-21-3 | | 0.0595 | mg |
| | | | В | Nickel (Ni) | 7440-02-0 | | 2.6775 | mg |
| | | | Supplier | Iron (Fe) | 7439-89-6 | | 3.6805 | mg |
| | | | Supplier | Copper (Cu) | 7440-50-8 | | 1.9975 | mg |
| Glass Encapsulation | 23.5 | mg | Supplier | Boron Trioxide (B2O3) | 1303-86-2 | | 0.705 | mg |
| | | | А | Lead Oxide (PbO) | 1317-36-8 | 7c | 14.382 | mg |
| | | | В | Antimony Trioxide (Sb2O3) | 1309-64-4 | | 0.0118 | mg |
| | | | Supplier | Potassium Monoxide (K2O) | 12136-45-7 | | 0.8813 | mg |
| | | | Supplier | Silica Crystalline (SiO2) | 14808-60-7 | | 7.52 | mg |
| Marking Ink | 0.01953 | mg | Supplier | Titanium Dioxide (TiO2) | 13463-67-7 | | 0.004 | mg |
| | | | Supplier | Formaldehyde, polymer with 4,4-(1- methylethylidene)bisphenol | 25085-75-0 | | 0.0052 | mg |
| | | | Supplier | Proprietary | Proprietary Data | | 0.0009 | mg |
| | | | Supplier | Silica Amorphous (SiO2) | 7631-86-9 | | 0.001 | mg |
| | | | Supplier | Carbon Black (C) | 1333-86-4 | | 0.0013 | mg |
| | | | Supplier | Diethylene glycol 2-ethyhexyl-ether | 1559-36-0 | | 0.0025 | mg |
| | | | Supplier | Amino Resin | 68002-20-0 | | 0.0033 | mg |
| | | | Supplier | 2,2,4-Trimethyl-1,3-pentanediol di is Obutyrate | 6846-50-0 | | 0.0013 | mg |
| Plating | 2.626 | mg | Supplier | Tin (Sn) | 7440-31-5 | | 2.626 | mg |